HALOGEN

FREE



Vishay Semiconductors

Ultrafast Rectifier, 8 A FRED Pt®



PRIMARY CHARACTERISTICS								
I _{F(AV)}	8 A							
V_{R}	600 V							
V _F at I _F	0.84 V							
t _{rr} (typ.)	65 ns							
T _J max.	175 °C							
Package	TO-220AC 2L							
Circuit configuration	Single							

FEATURES

- State of the art low forward voltage drop
- Ultrafast recovery time
- 175 °C operating junction temperature
- · Low leakage current
- True 2 pin package
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

DESCRIPTION

State of the art, ultralow V_F , soft-switching ultrafast rectifiers optimized for Discontinuous (Critical) Mode (DCM) Power Factor Correction (PFC).

The minimized conduction loss, optimized stored charge and low recovery current minimized the switching losses and reduce over dissipation in the switching element and snubbers.

The device is also intended for use as a freewheeling diode in power supplies and other power switching applications.

APPLICATIONS

AC-DC SMPS 70 W to 400 W

e.g. laptop and printer AC adaptors, desktop PC, TV and monitor, games units and DVD AC/DC power supplies.

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	V_{RRM}		600	V
Average rectified forward current in DC	I _{F(AV)}	T _C = 155 °C	8	^
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C	120] A
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C

ELECTRICAL SPECIFICATIONS (T _J = 25 °C unless otherwise specified)										
PARAMETER	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS					
Breakdown voltage, blocking voltage	V _{BR} , V _R	Ι _R = 100 μΑ	600	-	-					
Famoured coaltains	V _F	I _F = 8 A	-	0.97	1.07	V				
Forward voltage	VF	I _F = 8 A, T _J = 150 °C	-	0.84	0.90					
Reverse leakage current		$V_R = V_R$ rated	-	0.01	9					
neverse leakage current	I _R	$T_J = 150$ °C, $V_R = V_R$ rated	-	5	50	μΑ				
Junction capacitance	C _T	V _R = 600 V	-	6	-	pF				
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8	-	nΗ				



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DYNAMIC RECOVERY CHARACTERISTICS (T _J = 25 °C unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS		
Reverse recovery time		$I_F = 1 A, dI_F/dt = 100$	-	65	100				
		$I_F = 8 \text{ A}, dI_F/dt = 100$	-	150	250				
	t _{rr}	T _J = 25 °C		-	180	-	ns -		
		T _J = 125 °C	l _F = 8 A, dl _F /dt = 200 A/μs,	-	240	-			
Peak recovery current		T _J = 25 °C		-	15	-	A		
	IRRM	T _J = 125 °C	$V_{\rm R} = 390 \text{ V}$	-	19	-			
Reverse recovery charge	0	T _J = 25 °C] "	-	1500	-	nC		
	Q _{rr}	T _J = 125 °C		-	2400	-	IIC		

THERMAL - MECHANICAL SPECIFICATIONS										
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS				
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	ı	175	°C				
Thermal resistance, junction-to-case	R _{thJC}		ı	2.0	2.6					
Thermal resistance, junction-to-ambient	R _{thJA}	Typical socket mount	-	-	70	°C/W				
Typical thermal resistance, case-to-heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-					
Weight			-	2	-	g				
weight			ı	0.07	-	OZ.				
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)				
Marking device Case style TO-220AC 2L				ETL	0806					





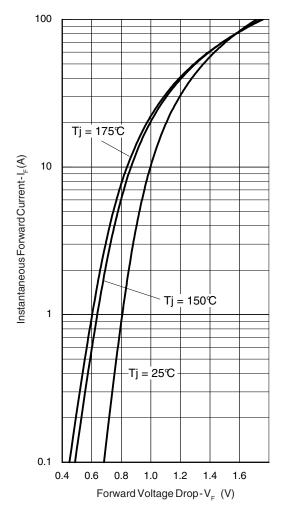


Fig. 1 - Typical Forward Voltage Drop Characteristics

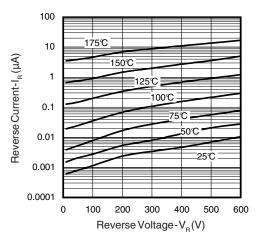


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

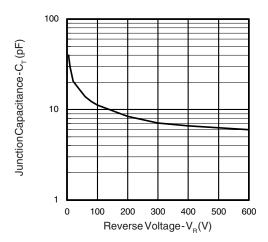


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

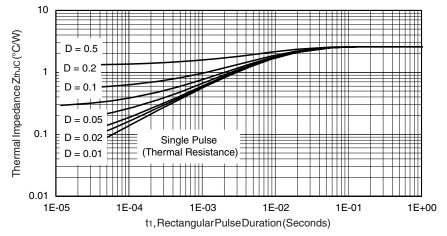


Fig. 4 - Maximum Thermal Impedance Z_{thJC} Characteristics



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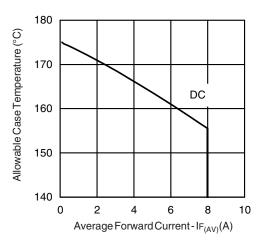


Fig. 5 - Maximum Allowable Case Temperature vs.
Average Forward Current

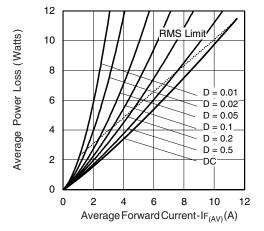


Fig. 6 - Forward Power Loss Characteristics

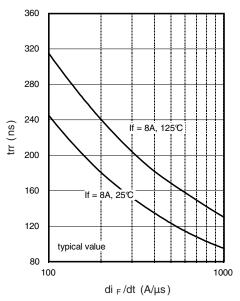


Fig. 7 - Typical Reverse Recovery vs. dl_F/dt

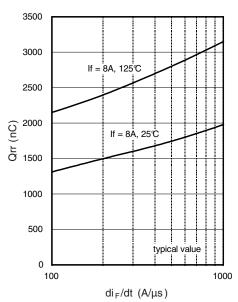
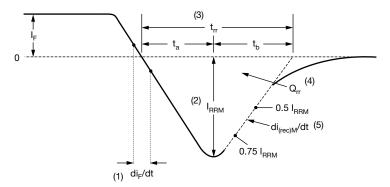


Fig. 8 - Typical Stored Charge vs. dl_F/dt

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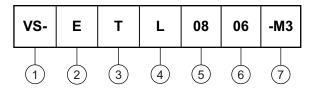


- (1) di_F/dt rate of change of current through zero crossing
- (4) \mathbf{Q}_{rr} area under curve defined by \mathbf{t}_{rr} and \mathbf{I}_{RRM}
- (2) I_{RRM} peak reverse recovery current
- $Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$
- (3) t_{rr} reverse recovery time measured from zero crossing point of negative going I_F to point where a line passing through 0.75 I_{RRM} and 0.50 I_{RRM} extrapolated to zero current.
- (5) $di_{(rec)M}/dt$ peak rate of change of current during t_b portion of t_{rr}

Fig. 9 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

Device code



Vishay Semiconductors product

2 - Circuit configuration:

E = single

3 - T = 2L TO-220AC

4 - L = hyperfast recovery time

5 - Current code: 08 = 8 A

6 - Voltage code: 06 = 600 V

7 - Environmental digit:

-M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)								
PREFERRED P/N BASE QUANTITY PACKAGING DESCRIPTION								
VS-ETL0806-M3	50	Antistatic plastic tubes						

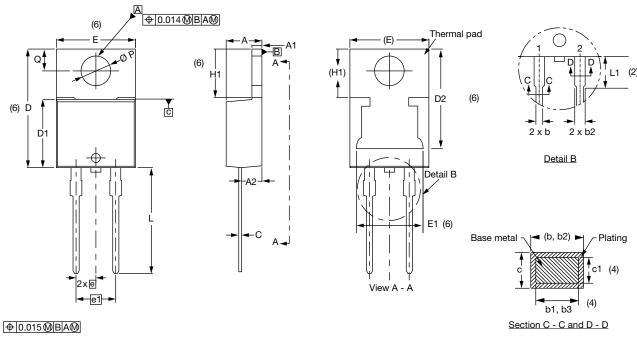
LINKS TO RELATED DOCUMENTS								
Dimensions <u>www.vishay.com/doc?96156</u>								
Part marking information	www.vishay.com/doc?95391							



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TO-220AC 2L

DIMENSIONS in millimeters and inches



Lead tip

Conforms to JEDEC® outline TO-220AC

SYMBOL	MILLIN	MILLIMETERS		INCHES		NOTES		MILLIN	IETERS	INC	HES	NOTES
STWIBUL	MIN.	MAX.	MIN.	MAX.	NOTES		SYMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
Α	4.25	4.65	0.167	0.183			D2	11.68	13.30	0.460	0.524	6, 7
A1	1.14	1.40	0.045	0.055			E	10.11	10.51	0.398	0.414	3, 6
A2	2.50	2.92	0.098	0.115			E1	6.86	8.89	0.270	0.350	6
b	0.69	1.01	0.027	0.040			е	2.41	2.67	0.095	0.105	
b1	0.38	0.97	0.015	0.038	4		e1	4.88	5.28	0.192	0.208	
b2	1.20	1.73	0.047	0.068			H1	6.09	6.48	0.240	0.255	6
b3	1.14	1.73	0.045	0.068	4		L	13.52	14.02	0.532	0.552	
С	0.36	0.61	0.014	0.024			L1	3.32	3.82	0.131	0.150	2
с1	0.36	0.56	0.014	0.022	4		ØΡ	3.54	3.91	0.139	0.154	
D	14.85	15.35	0.585	0.604	3		Q	2.60	3.00	0.102	0.118	
D1	8.38	9.02	0.330	0.355								

Notes

- $^{(1)}$ Dimensioning and tolerancing as per ASME Y14.5M-1994
- (2) Lead dimension and finish uncontrolled in L1
- (3) Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Dimension b1, b3, and c1 apply to base metal only
- (5) Controlling dimensions: inches
- (6) Thermal pad contour optional within dimensions E, H1, D2, and E1
- (7) Outline conforms to JEDEC® TO-220, except D2



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